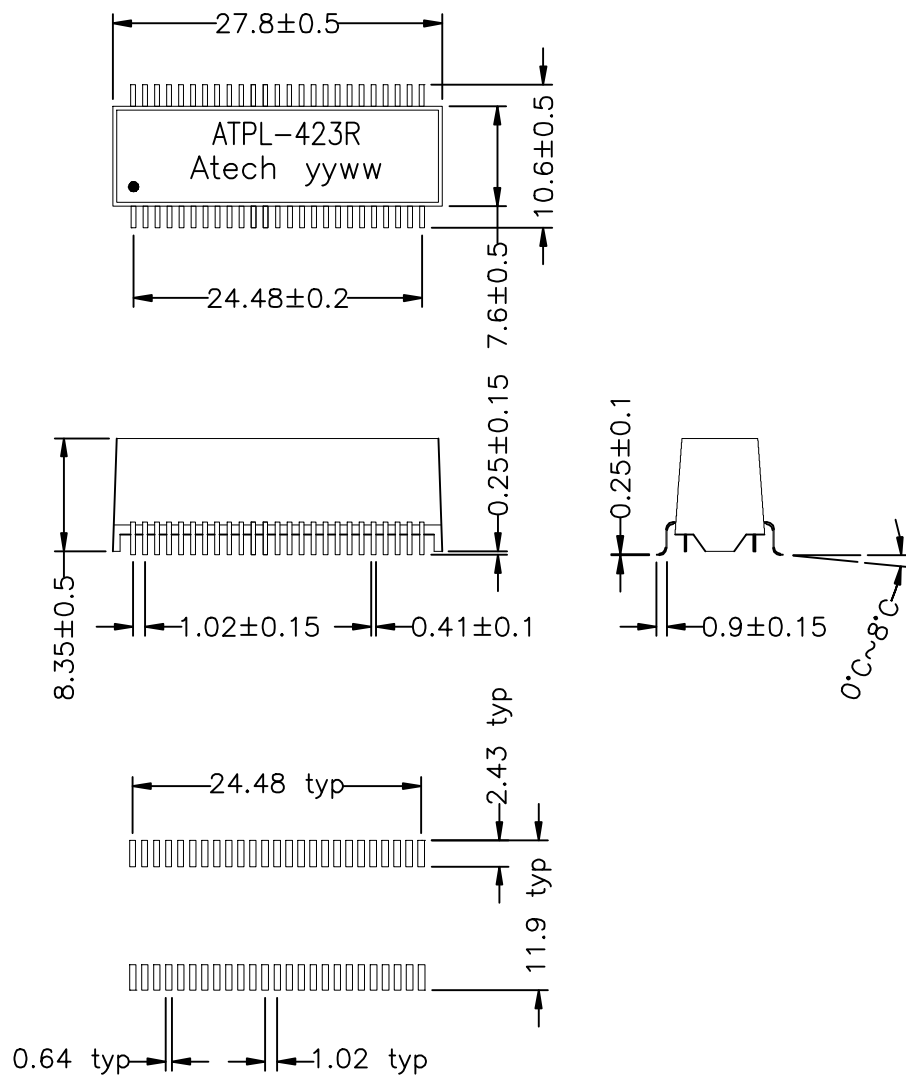
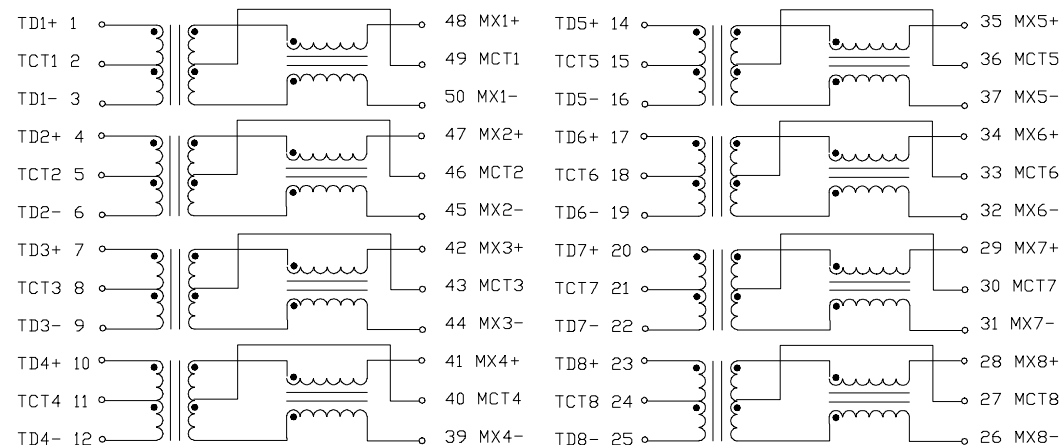




SUGGESTED PAD LAYOUT

TOLERANCES : xx.x0±0.25
0.xx±0.05

UNIT : mm



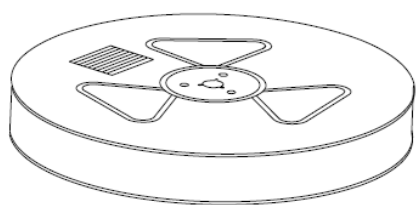
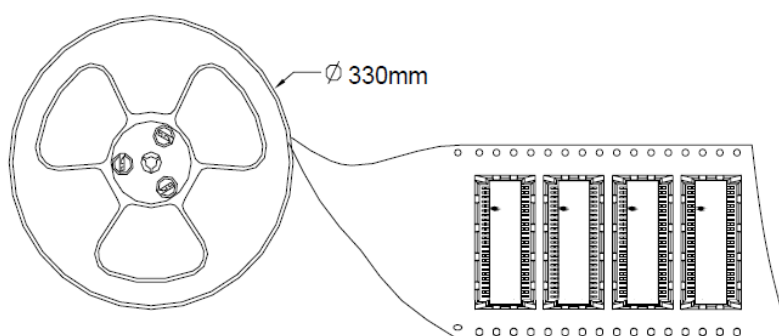
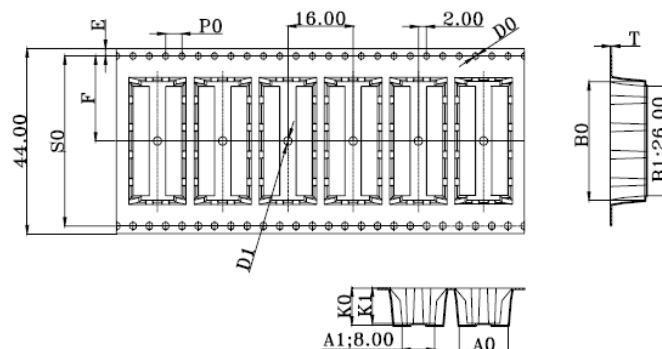
ELECTRICAL CHARACTERISTICS :

1. INSULATION HI-POT : 1500 Vrms/1mA, 60Sec.
2. TURN RATIO (±5%) : 1CT : 1CT
3. OCL : 350uH MIN. 8mA/DC Bias (@100kHz, 0.1V)
4. CROSS TALK : 1-100kHz = -30dB MIN.
5. INSERTION LOSS (1MHz - 100MHz) : -1.1dB MAX.
6. RETURN LOSS (dB MIN. @100Q) :

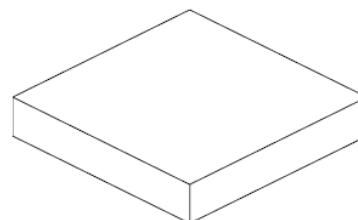
1-30MHz	40MHz	50MHz	60-80MHz	100MHz
-18	-14.4	-13.1	-12	-10
7. COMMON MODE REJECTION : 1-100kHz = -30dB MIN.
8. RoHS COMPLIANT

								TITLE 100/1000 BASE-TRANSFORMER	
								DWG. NO. ATPL-423R	
	RELEASE	05/04/2011	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:		DRAW SHIRLEY
REVISIONS						05/04/11			

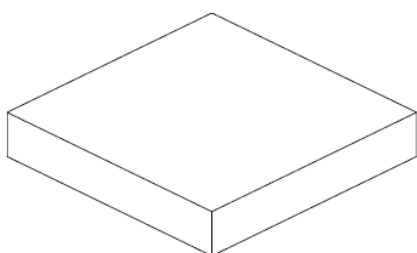
Package :



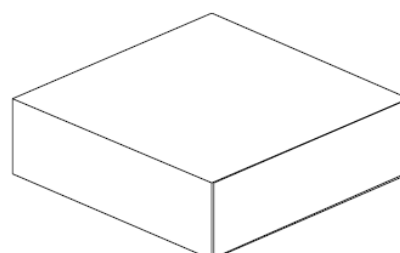
two reel



Inner Carton



two Inner Carton



Export Carton

Package Quantity:

One Reel=400

One Inner Carton=400*2=800Pcs

One Export Carton=800*2=1600Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max